	REVISIONS																									
LTR						DESCRIPTION						DAT	E (YR	- <b>M</b> O-	DA)	A	PPR	OVED	)							
А	Made throu	tech ghou	nnio ut.	cal	cha	nges	in	tab	le 1		Edit	ori	al c	har	nges				1989	SEF	2 12	!	W	rck	mo	₽.
REV																										
SHEET		_										L						L							_	
REV		+	4	_							<u> </u>	H	Н		Ш	_	-	ļ	<u> </u>	_		_	_			Н
SHEET		ᆉ		لــ	Щ				_	_	-	Ш			-		-		<u> </u>	<b>-</b>		-	-		_	$\vdash$
REV ST		$\vdash$	RE	V EET		A		Α	Н	A	Α	A	Α	Α_	Н		-	_	-	$\vdash$	_	-			$\vdash$	Н
PMIC N/A  STANDARDIZED  MILITARY  DRAWING  THIS DRAWING IS AVAILABLE				PREPARED BY  CHECKED BY  Tim H. Moh  APPROVED BY  William X. Zeckman						DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444  MICROCIRCUIT, DIGITAL, ADVANCED SCHOTTKY TTL, NAND DRIVER, MONOLITHIC SILICON				,												
FOR USE	BY ALL D AGENCIE TMENT C	DEPA ES OF	RTM THI	ENT E		DRAWING APPROVAL DATE  16 MAY 1988  REVISION LEVEL  A				_	SIZE CAGE CODE 67268 5962-87  SHEET 1 OF 9			77(	66											

DESC FORM 193 SEP 87

\* U.S. GOVERNMENT PRINTING OFFICE: 1987 — 748-129/60911 5962-E1469

DISTRIBUTION STATEMENT A. Approved for public release; distribution is unlimited.

1. SCOPE			
1.1 <u>Scope</u> . This drawing des with 1. <del>2.1</del> of MIL-STD-883, "Pro non-JAN devices".	cribes device requi visions for the use	rements for class B of MIL-STD-883 in c	microcircuits in accordance onjunction with compliant
1.2 Part number. The comple	te part number shal	l be as shown in the	following example:
5962-87766   	01 Device type	R	X   
	(1.2.1)	(1.2.2)	MIL-M-38510
1.2.1 <u>Device type</u> . The devi	ce type shall ident	ify the circuit func	tion as follows:
Device type	Generic number	Circuit function	<u>on</u>
01	54AS804	Hex 2-input NA	ND driver
1.2.2 <u>Case outlines</u> . The ca as follows:	se outlines shall b	e as designated in a	opendix C of MIL-M-38510, and
Outline letter		Case out	tline
R		D-8 (20-lead, 1.060" package	$\times$ .310 $^{*}$ $\times$ .200 $^{*}$ ), dual-in-line
\$ 2		F-9 (20-lead, .540" :	c .300" x .100"), flat package 358" x 0.358" x .100"), square ackage
1.3 Absolute maximum ratings			
Supply voltage range Input voltage range Storage temperature range Maximum power dissipation Lead temperature (solderin Thermal resistance, junction temperature (T <sub>J</sub> )	(P <sub>D</sub> ) 1/		to +7.0 V dc :-18 mA to +7.0 V +150 C
1.4 Recommended operating cor	nditions.		
Supply voltage range (Y <sub>CC</sub> ) Minimum high level input vo Maximum low level input vo Case operating temperature	voltage (V <sub>IH</sub> ) oltage (V <sub>IL</sub> )	2.0 V 0.8 V	nimum to +5.5 V maximum. +125°C
 1/ Must withstand the added P <sub>D</sub>	due to the short c	rcuit test, e.g., I <sub>O</sub>	•

SIZE

DEFENSE ELECTRONICS SUPPLY CENTER
DAYTON, OHIO 45444

DESC FORM 193A
SEP 87

★ U. S, GOVERNMENT PRINTING OFFICE: 1988--550-547

SHEET

5962-87766

REVISION LEVEL

**STANDARDIZED** 

**MILITARY DRAWING** 

## 2. APPLICABLE DOCUMENTS

2.1 Government specification, standard, and bulletin. Unless otherwise specified, the following specification, standard, and bulletin of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this drawing to the extent specified herein.

**SPECIFICATION** 

MI! ITARY

MIL-M-38510

Microcircuits, General Specification for.

STANDARD

**MILITARY** 

MIL-STD-883

Test Methods and Procedures for Microelectronics.

BULLETIN

MILITARY

MIL-BUL-103

- List of Standardized Military Drawings (SMD's).

(Copies of the specification, standard, and bulletin required by manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting activity.)

2.2 <u>Order of precedence</u>. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing shall take precedence.

## 3. REQUIREMENTS

- 3.1 Item requirements. The individual item requirements shall be in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices" and as specified herein.
- $3.2~\underline{\text{Design}}$ , construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.
  - 3.2.1 Terminal connections. The terminal connections shall be as specified on figure 1 .
  - 3.2.2 Truth table. The truth table shall be as specified on figure 2.
- 3.2.3 Case outlines. The case outlines shall be in accordance with 1.2.2 herein.
- 3.3 Electrical performance characteristics. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full case operating temperature range.
- 3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.
- 3.5 Marking. Marking shall be in accordance with MIL-STD-883 (see 3.1 herein). The part shall be marked with the part number listed in 1.2 herein. In addition, the manufacturer's part number may also be marked as listed in MIL-BUL-103 (see 6.6 herein).

STANDARDIZED MILITARY DRAWING	SIZE <b>A</b>	Δ					
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		ï	REVISION LEVEL		SHEET 3		

DESC FORM 193A

SEP 87

± U. S. GÖVERNMENT PRINTING OFFICE: 1988—549-904

TABLE I. Electrical performance characteristics. Conditions 1/ -55°C < T<sub>C</sub> < +125°C unless otherwise specified Limits Test Symbol | Group A Unit subgroups Min | Max V<sub>CC</sub> = 4.5 V V<sub>IL</sub> = 0.8 V High level output ۷он  $I_{OH} = -2 mA$ 1,2,3 2.5 ٧ voltage VIH = 2.0 V  $I_{OH} = -3 \text{ mA}$ ٧ 1,2,3 2.4  $I_{OH} = -40 \text{ mA}$ 2.0 ٧ 1,2,3 V<sub>CC</sub> = 4.5 V V<sub>IL</sub> = 0.8 V V<sub>IH</sub> = 2.0 V <u>2/</u> Low level output 1,2,3 0.5 ٧ VOL  $I_{OL} = 40 \text{ mA}$ voltage VCC = 4.5 V ٧ Input clamp VIC  $I_{IN} = -18 \text{ mA}$ 1,2,3 -1.2 voltage Low level input V<sub>CC</sub> = 5.5 V 1,2,3 -0.5 mΑ IIL VIN = 0.4 V current Inputs not under test # 4.5 V V<sub>CC</sub> = 5.5 V V<sub>IN</sub> = 2.7 V High level input I<sub>IH1</sub> 1,2,3 20 μΑ čurrent Inputs not under test = 0.0 V  $V_{CC} = 5.5 V$ 1,2,3 0.1 mΑ I<sub>IH2</sub> VIN = 7.0 V Inputs not under test = 0.0 V  $V_{CC} = 5.5 \text{ V} \\ V_{OUT} = 2.25 \text{ V} \quad 3/$ Output current 10 1,2,3 -50 1-200 mΑ V<sub>CC</sub> = 5.5 V V<sub>IN</sub> = 0.0 V Supply current 1,2,3 5 ICCH mΑ V<sub>CC</sub> = 5.5 V V<sub>IN</sub> = 4.5 V ICCL 1,2,3 27 mΑ  $\begin{array}{l} \text{GND} & \leq \text{VIL} & \leq \text{VOL} \\ \text{VOH} & \leq \text{VIH} & \leq \text{VCC} \\ \text{See} & \textbf{4.3.1c} \end{array}$ Functional tests 7,8 See footnotes at end of table. **STANDARDIZED** SIZE A 5962-87766 **MILITARY DRAWING DEFENSE ELECTRONICS SUPPLY CENTER** REVISION LEVEL SHEET DAYTON, OHIO 45444

DESC FORM 193A SEP 87

★ U. S. GOVERNMENT PRINTING OFFICE: 1988-550-547

TABLE I.	Electrica	n) performance characteristics - (	Continued.			
Test	Symbol	Conditions 1/   -55°C < T <sub>C</sub> < +125°C unless otherwise specified	Group A  subgroups	Limi		Unit
Propagation delay time A, B to Y	t <sub>PLH</sub> ,	V <sub>CC</sub> = 4.5 V to 5.5 V   C <sub>1</sub> = 50 pF	9	1	5	ns
, 0 33 .	i THL	iRL = 500Ω <u>4/</u> I	10, 11	1	   5 	ns

1/ Unused inputs that do not directly control the pin under test shall be > 2.5 V or  $\le 0.4$  V, and shall not exceed 5.5 V or go less than 0.0 V. No inputs shall be floating.
2/ All outputs shall be tested. In the case where only one input at V<sub>II</sub> maximum or V<sub>IH</sub> minimum produces the proper output state, the test shall be performed with each input being selected as

the  $V_{IL}$  maximum or  $V_{IH}$  minimum input. 3/ The output conditions have been chosen to produce a current that closely approximates one half of the true short circuit output current,  $I_{\rm OS}$ . Not more than one output shall be tested at a time and the duration of the test shall not exceed one second.

- Propagation delay limits are based on single output switching. Unused outputs = 3.5 V or  $\leq$  0.3 V. The load circuit shall consist of the specified  $R_{\rm L}$  and  $C_{\rm L}$  in series, with  $R_{\rm L}$  tied to  $V_{\rm CC}$  and  $C_{\rm L}$  tied to GND. The device test point shall be the node between  $C_{\rm L}$  and  $R_{\rm L}$ . Voltage waveforms shall be in accordance with method 3003 of MIL-STD-883, with measurement points at 10 percent and 90 percent.
- 3.6 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-BUL-103 (see 6.6 herein). The certificate of compilance submitted to DESC-ECS prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.
- 3.7 Certificate of conformance. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.
- 3.8 Notification of change. Notification of change to DESC-ECC shall be required in accordance with MIL-STD-883 (see 3.1 herein).
- 3.9 Verification and review. DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.
  - 4. QUALITY ASSURANCE PROVISIONS
- 4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with section 4 of MIL-M-38510 to the extent specified in MIL-STD-883 (see 3.1 herein).

STANDARDIZED MILITARY DRAWING	SIZE A		5962-87766	
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		REVISION LEVEL	SHEET 5	

DESC FORM 193A SEP 87

- 4.2 <u>Screening</u>. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
  - a. Burn-in test, method 1015 of MIL-STD-883.
    - (1) Test condition A or D using the circuit submitted with the certificate of compliance (see 3.6 herein).
    - (2)  $T_A = +125^{\circ}C$ , minimum.
  - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (per method 5005, table I)
Interim electrical parameters (method 5004)	
Final electrical test parameters (method 5004)	1*,2,3,7,8,9,10,11
Group A test requirements (method 5005)	1,2,3,7,8,9,10,11
Groups C and D end-point lelectrical parameters (method 5005)	1,2,3

<sup>\*</sup> PDA applies to subgroup 1.

- 4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method 5005 of MIL-SID-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.
  - 4.3.1 Group A inspection.
    - a. Tests shall be as specified in table II herein.
    - b. Subgroups 4, 5, and 6 in table I, method 5005 of MIL-STD-883 shall be omitted.
    - c. Subgroups 7 and 8 shall verify the truth table specified on figure 2 herein.

STANDARDIZED MILITARY DRAWING	SIZE A		5962	2-87766		
DEFENSE ELECTRONICS SUPPLY CENTER DAYTON, OHIO 45444		REVISION LEVEL		SHEET 6		

DESC FORM 193A SEP 87

± U. S. GOVERNMENT PRINTING OFFICE: 1986-560-547

Ţ	[		[
Device type	01	Device type	01
Case outlines	R, S, and 2	Case outlines	R, S, and 2
  Terminal number	   Terminal symbol	  Terminal number	l Terminal symbol
1	1A I	11	4Y
2	1B	12	4A
3	1Y	13	   4B
4	   2A	14	5Y
5	l     2B	15	5A
6	2Y	16	5B
7	3A i	17	6Y
8	3B	18	6A
9	3Y	19	6B
10	GND I	l 20	v <sub>CC</sub>

FIGURE 1. Terminal connections.

I	Inp	uts	   Output
T	A	l l B	Y
T	н	l H	L
l	L	   X	   H
į	X	j '' '   1.	l i
<u>i</u>		i -	<u> </u>

FIGURE 2. Truth table.

H = High level
L = Low level
X = Irrelevant

STANDARDIZED
MILITARY DRAWING
DEFENSE ELECTRONICS SUPPLY CENTER
DAYTON, OHIO 45444

DESC FORM 193A SEP 87

- 4.3.2 Groups C and D inspections.
  - a. End-point electrical parameters shall be as specified in table II herein.
  - b. Steady-state life test conditions, method 1005 of MIL-STD-883.
    - Test condition A or D using the circuit submitted with the certificate of compliance (see 3.6 herein).
    - (2)  $T_A = +125^{\circ}C$ , minimum.
    - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.
- 5. PACKAGING
- 5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.
  - 6. NOTES
- 6.1 Intended use. Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for OEM application. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, the device specified herein will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.
- 6.2 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-481 using DD Form 1693, Engineering Change Proposal (Short Form).
- 6.4 Record of users. Military and industrial users shall inform Defense Electronics Supply Center when a system application requires configuration control and the applicable SMD. DESC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronics devices (FSC 5962) should contact DESC-ECC, telephone (513) 296-6022.
- 6.5 Comments. Comments on this drawing should be directed to DESC-ECC, Dayton, Ohio 45444, or telephone 513-296-8525.

STANDARDIZED
MILITARY DRAWING
DEFENSE ELECTRONICS SUPPLY CENTER
DAYTON, OHIO 45444

SIZE
A
5962-87766

REVISION LEVEL
A
8

DESC FORM 193A SEP 87

**★ U. S. GÖVERNMENT PRINTING OFFICE: 1988--549-904** 

6.6 Approved source of supply. An approved source of supply is listed in MIL-BUL-103. Additional sources will be added to MIL-BUL-103 as they become available. The vendor listed in MIL-BUL-103 has agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DESC-ECC. The approved source of supply listed below is for information purposes only and is current only to the date of the last action of this document.

Military drawing part number	Vendor     CAGE     number	Vendor similar part number <u>1</u> /
5962-8776601RX	01295	SNJ54AS804BJ
5962-8776601SX	01295	SNJ54AS804BW
5962-87766012X	01295	SNJ54AS804BFK

1/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE number Vendor name and address

01295

Texas Instruments, Incorporated PO Box 6448 Midland, TX 79711

STANDARDIZED
MILITARY DRAWING
DEFENSE ELECTRONICS SUPPLY CENTER
DAYTON, OHIO 45444

SIZE A 5962-87766

REVISION LEVEL SHEET 9

DESC FORM 193A SEP 87

± U. S. GOVERNMENT PRINTING OFFICE: 1988---550-547